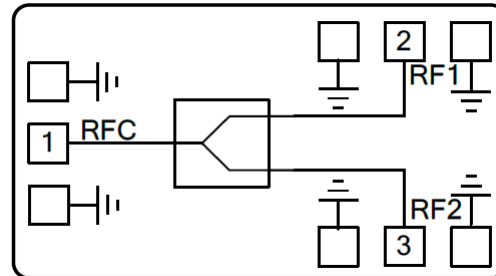


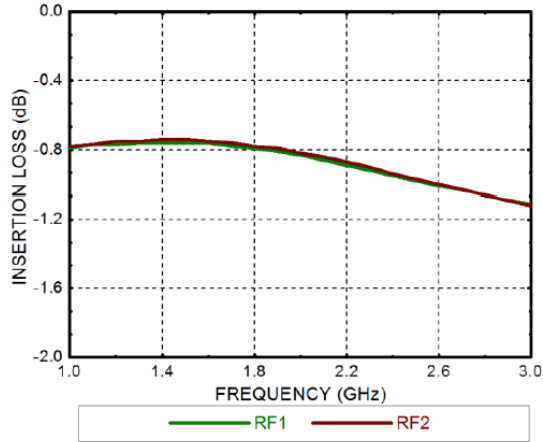
**Features**

- Frequency: 1-3GHz
- Insertion Loss: 0.9dB
- Input/Output: 50Ω matched
- Die Size: 1.5 x 1.0 x 0.1 mm

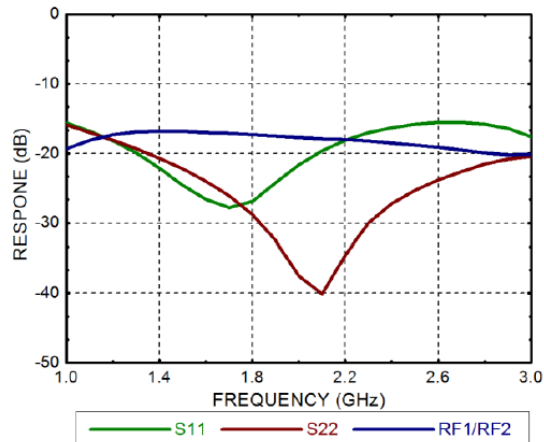
**Functional Block Diagram**

**Electrical Specifications**
**TA = +25°C, Pin=0dBm**

Parameters	Min.	Typ.	Max.	Units
<b>Frequency</b>		<b>1-3</b>		<b>GHz</b>
<b>Insertion Loss</b>		<b>0.9</b>		<b>dB</b>
<b>Flatness</b>		<b>±0.2</b>		<b>dB</b>
<b>Isolation</b>		<b>18</b>		<b>dB</b>
<b>Return Loss</b>		<b>20</b>		<b>dB</b>

**Insertion Loss**

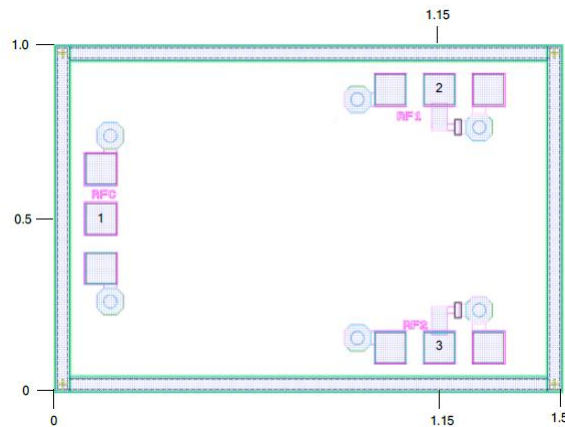


**Isolation & Return Loss**



**Outline Drawing:**

All Dimensions in mm



**Pad Description**

Pad	Function	Description
1	RFC	RF Common Port
2,3	RF1,RF2	RF Branch Port

**Maximum Ratings:**

1. Maximum input power: +37dBm
2. Operating temperature: -55°C to +85°C
3. Storage temperature: -65°C to +175°C